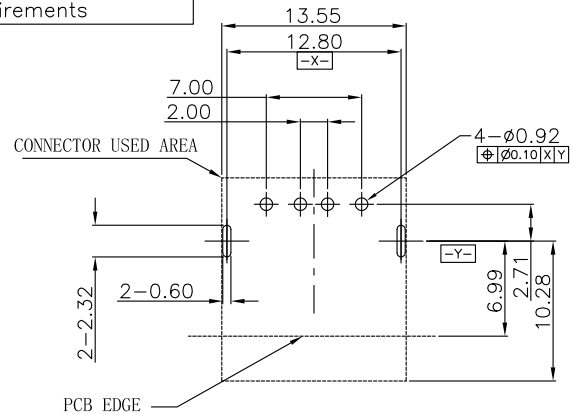
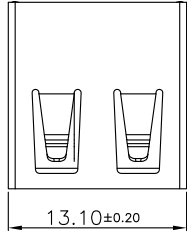
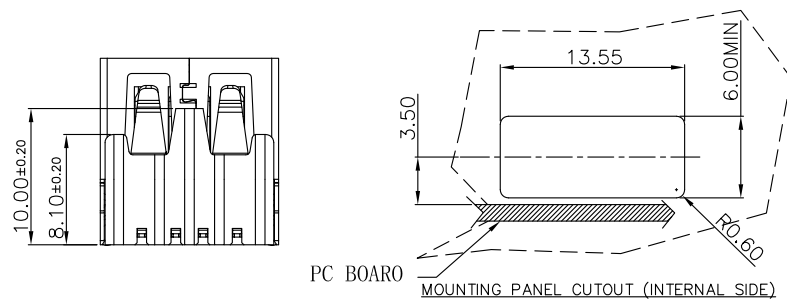
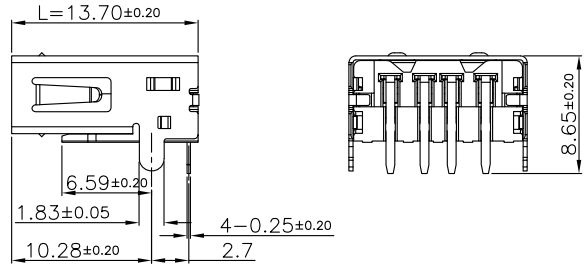
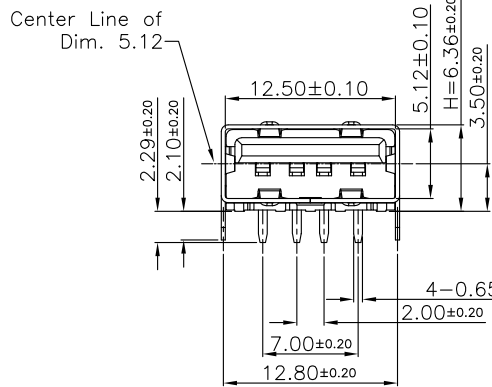


The product using material and processing must conform to the "WI-PZ-001" HSF technical standard control requirements

RoHS



RECOMMENDED PCB LAYOUT(TOP VIEW)  
GENERAL TOLERANCES:±0.05



NOTE:

- 1.MATERIAL SPECIFICATION:
  - 1-1.HOUSING:LCP BLACK UL94V-0
  - 1-2.CONTACTS:COPPER ALLOY.
  - 1-3.SHELL:COPPER ALLOY.
- 2.PLATING SPECIFICATION:
  - 2-1.CONTACTS:  
Ni 50u" MIN. UNDER PLATED OVER ALL.  
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
  - 2-2. SHELL:  
Ni 30u" MIN. UNDER PLATED OVER ALL.
- 3.MECHANICAL PERFORMANCE:
  - 3-1.INSERTION FORCE: 3.57kgf MAX
  - 3-2.REMOVAL FORCE: 1.02kgf MIN
  - 3-3.DURABILITY: 1500CYCLES.
- 4.ELECTRICAL PERFORMANCE:
  - 4-1.CURRENT RATING:1.5A
  - 4-2.VOLTAGE RATING:30V MAX
  - 4-3.CONTACT RESISTANCE: 30m Ohm Max.
  - 4-4.INSULATION RESISTANCE: 1000MΩ MIN
  - 4-5.DIELECTRIC WITHSTANDING VOLTAGE: 500V AC Min
- 5.ENVIRONMENTAL PERFORMANCE:  
OPERATING TEMPERATURE: -20°C~+85°C.
- 6.PACKAGE SPEC: 260Pcs/REEL, 2080Pcs/CARTON

WLU2F9-04 1 X X 0012

PLATING: 1-G/F  
2-AU 3U"  
5-AU 15U"  
6-AU 30U"  
COLOUR: A:BLACK  
K:WHITE

REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART. NO: WLU2F9-041XX0012	DWG. NO: ENDE05	
A0	NEW RELEASE	21. 01. 13		LINEAR	ANGLES	APPROVED	Wang_jr	21. 01. 13			
			0.0±0.35	X° REF±6°	DESIGNER	Ding_bo	21. 01. 13	TITLE: USB2.0 AF 单层 DIP 插板 打直脚	REV: A0	SHEET: 1/1	
			UNIT: mm	0.00±0.25	X° ±3°	DRAWN	Ou_jian	21. 01. 13			
			SIZE: A4	0.000±0.10	X° X'±2°						